



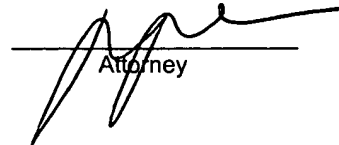
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27,922

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PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

### Application of:

Applicant : Lawrence E. Gebhart et al.  
Appln. No. : 10/804,841  
Filed : March 19, 2004  
Title : ELECTROPLATING CELL WITH HYDRODYNAMICS  
FACILITATING MORE UNIFORM DEPOSITION ACROSS A  
WORKPIECE DURING PLATING  
Docket No. : 461987-024  
Art Unit : 1742

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

### INFORMATION DISCLOSURE STATEMENT

Pursuant to 37 C.F.R. §1.56, the Examiner's attention is directed to the references listed on the attached Information Disclosure Citation. Copies of all non-patent literature references are provided herewith.

It is to be understood that the present submission of art is in no way intended to be a waiver of any arguments or defenses available to the applicant under the rules of the U.S. Patent and Trademark Office and the statutes of the United States.

No fee is required. The Commissioner is authorized to charge any additional fees required by this paper or to credit any overpayment to Deposit Account No. 20-0809.

Respectfully submitted:

By:

  
Mark P. Levy

Reg. No. 27,922

Application No.: 10/804,841  
Docket No.: 461987-024  
Information Disclosure Statement

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INFORMATION DISCLOSURE CITATION

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Docket: 461987-024	Appln. No.: 10/804,841
Applicant: Lawrence E. Gebhart et al.	
Filed: 03/19/2004	Group: 1742

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\* Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION

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Applicant: Lawrence E. Gebhart et al.	
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